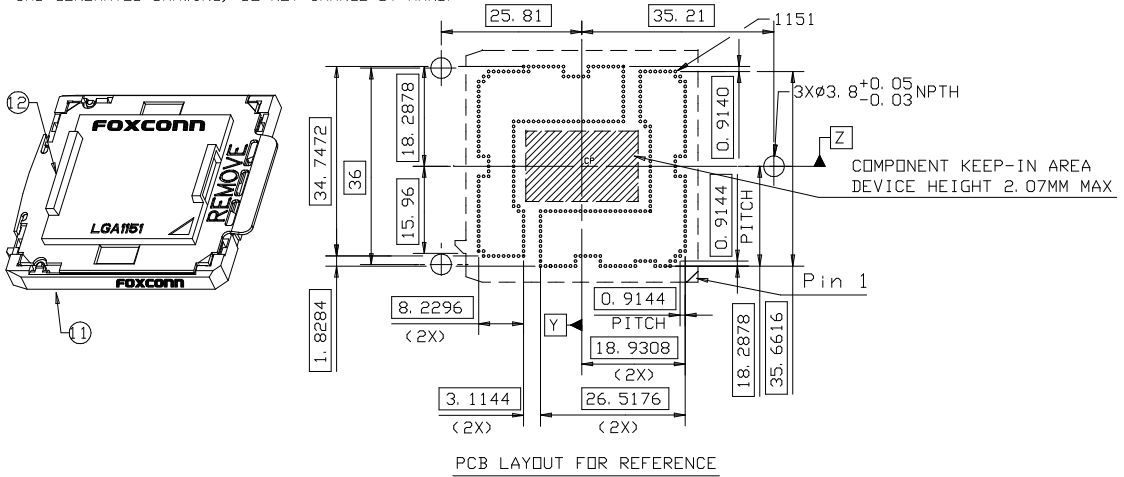
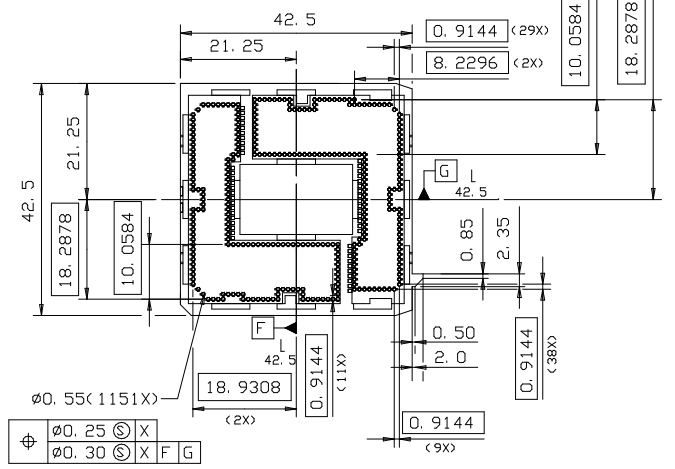
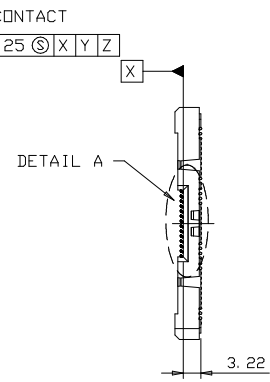
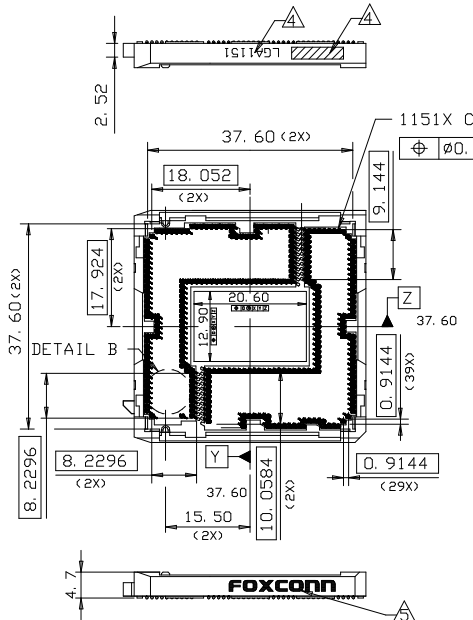
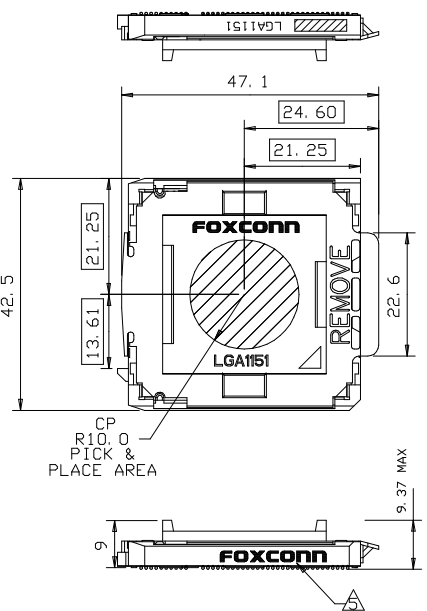
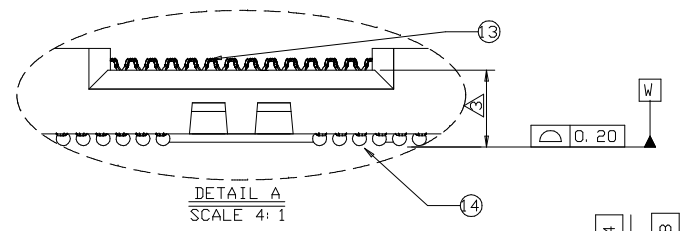


CAD GENERATED DRAWING, DO NOT CHANGE BY HAND.

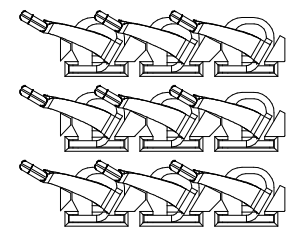
REV.	ECN. NO.	APPD.
A	BC-14-0031104	Dickie H



- NOTES:
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - MATERIAL: SOCKET BODY LCP, UL94V-0, BLACK;
CONTACT Cu Ni ALLOY, 1u" MIN. Au PLATING OVER 50u" MIN.
Ni UNDERPLATING ON CONTACT AREA;
PICK-UP CAP LCP, UL94V-0, BLACK;
SOLDERBALL LEAD FREE Sn/Ag/Cu BALL;
 - THICKNESS OF SOCKET (FROM SEATING PLANE TO THE BOTTOM OF SOLDER BALLS):
3.4±0.20mm AFTER SOLDERING PROCESS
 - DATE CODE & SOCKET NAME IS LOCATED APPROXIMATELY.
 - FOXCONN LOGO IS LOCATED APPROXIMATELY.
 - HARMFUL MATERIAL CONTROL PLEASE FOLLOWS DDC. NO. 'EPI12';
(COMPLIANT TO RoHS)
 - FOR GENERAL BOARD DESIGN, PLEASE REFER TO THE THERMAL AND MECHANICAL DESIGN GUIDELINES (TMDG) PROVIDED BY INTEL CORPORATION
 - THE CONCENTRATIONS OF Br&Cl CAN SATISFY REQUIREMENTS OF HALOGEN-FREE IN DOCUMENT 'EPI12'
 - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.



COMPONENT LIST<3H993921-4M41-02H>		
ITEM	DESCRIPTION	Q' TY
①	SOCKET BODY	1
②	PICK & PLACE CAP	1
③	CONTACT	1151
④	SOLDER BALL	1151



X. ± 0.30	X. ° ± 1°	UNITS	mm	NAME (INTENDED USE)	LGA 1151 H4 SOCKET	FOXCONN FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
. X ± 0.20	. X ° ±	MAT'L		PART NO. (INTENDED USE)	3H993921-4M41-02H	
. XX ± 0.10	. XX ° ±			APPD:	Nick Lin	TITLE: CUSTOMER DRAWING FOR LGA 1151 H4 SOCKET
. XXX ±	. XXX ° ±	FINISH		CHKD:	Dickie Huang	DWG NO.: 351-0000-1310
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						Tommy Tao 04/25/15

